

Date: - 3 Jan. 2007

Data Sheet Issue:- 1

Provisional Data

Phase Control Thyristor

Types N3930Z#120 to N3930Z#160

Development Type No.: NX188ZD160

Absolute Maximum Ratings

	VOLTAGE RATINGS		MAXIMUM LIMITS	UNITS
V_{DRM}	Repetitive peak off-state voltage, (note 1)		1200-1600	V
V_{DSM}	Non-repetitive peak off-state voltage, (note 1)		1200-1600	V
V_{RRM}	Repetitive peak reverse voltage, (note 1)		1200-1600	V
V_{RSM}	Non-repetitive peak reverse voltage, (note 1)	$\langle \bigcirc \rangle_{\wedge}$	1300-1700	V

	OTHER RATINGS	7	MAXIMUM LIMITS	UNITS
$I_{T(AV)M}$	Maximum average on-state current, T _{sin} =55°C,	(note 2)	3930	Α
$I_{T(AV)M}$	Maximum average on-state current. T _{sink} =85 °C,	(note)2)	2658	Α
$I_{T(AV)M}$	Maximum average on-state current T _{sink} =85°C,	(note 3)	1576	Α
I _{T(RMS)M}	Nominal RMS on-state current, T _{sink} =25°C, (note	2)	7820	Α
I _{T(d.c.)}	D.C. on-state current, T _{sink} =25°C, (note 4)	\rightarrow	6629	Α
I _{TSM}	Peak non-repetitive surge t _p =10ms, V _{rm} =0.6V _{RRM} , (note 5)		54.0	kA
I _{TSM2}	Peak non-repetitive surge t _p =10ms, V _{rm} ≤10V _r (no	ote 5)	59.4	kA
I ² t	I ² t capacity for fusing/t _p =10ms, V _m =0:6V _{RRM} , (note 5)		14.6×10 ⁶	A ² s
l ² t	I ² t capacity for fusing t _p =10ms, V _{rm} ≤10V, (note 5)	17.6×10 ⁶	A ² s
		(continuous, 50Hz)	75	
(di/dt) _{cr}	Critical rate of rise of on state current (Note 6)	(repetitive, 50Hz, 60s)	150	A/µs
		(non-repetitive)	300	
V_{RGM}	Peak reverse gate voltage	5	V	
P _{G(AV)}	Mean forward gate power	5	W	
P_{GM}	Peak forward gate power	30	W	
T _{j op}	Operating temperature range	-40 to +125	°C	
∕T _{stg}	Storage temperature range		-40 to +150	°C

- De-rating factor of 0.13% per °C is applicable for T_j below 25°C.
 Double side cooled, single phase; 50Hz, 180° half-sinewave.
- 3) Single side cooled, single phase; 50Hz, 180° half-sinewave.
- 4) Double side cooled.
- 5) Half-sinewaye, 125°C T_i initial.
- 6) $V_D=67\%V_{DRM}$, $I_{FG}=2A$, $t_r \le 0.5 \mu s$, $T_{case}=125^{\circ}C$.



Characteristics

	PARAMETER	MIN.	TYP.	MAX.	TEST CONDITIONS (Note 1)	UNITS
V_{TM}	Maximum peak on-state voltage	-	-	1.25	I _{TM} =5000A	V
V_{TM}	Maximum peak on-state voltage	-	-	1.45	I _{TM} =8000A	V
V _{T0}	Threshold voltage	-	-	0.841	Valid from 2000A to 6000A	V
r _T	Slope resistance	-	-	0.080	Valid Horri 2000A to 6000A	mΩ
(dv/dt) _{cr}	Critical rate of rise of off-state voltage	1000	-	-	V _D =80% V _{DRM} , linear ramp, gate o/c	V/μs
I _{DRM}	Peak off-state current	-	-	200	Rated V _{DRM}	mA
I _{RRM}	Peak reverse current	-	-	200/	Rated V _{RRM}	mA
V_{GT}	Gate trigger voltage	-	-	3/.0	T _i =25°C V _D =10V, I _T =3A	V
I _{GT}	Gate trigger current	-	-	√ 300 [✓]	V _D =10V, I _T =3A	mA
V_{GD}	Gate non-trigger voltage	-	-	0.25	Rated V _{DRM}	V
I _H	Holding current	-	-	1000	T _j =25°C	mA
t _{gd}	Gate-controlled turn-on delay time		0.7	1.0	V _D =67% V _{DRM} , I _T =1000A, di/dt=10A/μs,	μs
t _{gt}	Turn-on time	-	1.5	20	I _{FG} =2A, t _r =0.5μs, T _j =25°C	μs
Qrr	Recovered charge	-	4000	$\overline{}$		μC
Q _{ra}	Recovered charge, 50% Chord	-	2600	3200	√ _{TM} =4000A, t _p =2000μs, di/dt=10A/μs,	μC
Irr	Reverse recovery current	-	170	<u> </u>	V _r =50∨	Α
t _{rr}	Reverse recovery time, 50% Chord	- /	3/1			μs
t _q	Turn-off time	- (150 200	<u>)</u>	$ \begin{array}{l} I_{TM}\!\!=\!\!4000A, \ t_p\!\!=\!\!2000\mu s, \ di/dt\!\!=\!\!10A/\mu s, \\ V_r\!\!=\!\!50V, \ V_{dr}\!\!=\!\!67\%V_{DRM}, \ dV_{dr}\!/dt\!\!=\!\!20V/\mu s \\ I_{TM}\!\!=\!\!4000A, \ t_p\!\!=\!\!2000\mu s, \ di/dt\!\!=\!\!10A/\mu s, \\ V_r\!\!=\!\!50V, \ V_{dr}\!\!=\!\!67\%V_{DRM}, \ dV_{dr}\!/dt\!\!=\!\!200V/\mu s \end{array} $	μs
_	The second secon		\ <u>-</u>	0.011	Double side cooled	K/W
R_{thJK}	Thermal resistance, junction to heatsink	(- \	->	0.022	Single side cooled	K/W
F	Mounting force	27	-	47		kN
Wt	Weight) 1.7 1.2	-	Outline option ZC & ZT Outline option ZD & ZV	kg

Notes:-

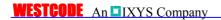
1) Unless otherwise indicated T_j=125°C.

2) For other clamp forces, please consult factory.

Notes on rupture rated packages.

This product is available with a non-rupture rated package.

For additional details on these products, please consult factory.



Notes on Ratings and Characteristics

1.0 Voltage Grade Table

Voltage Grade	$egin{array}{c} V_{DRM} \ V_{DSM} \ V_{RRM} \ V \end{array}$	V _{RSM} V	V _D /V _R DC V
12	1200	1300	810
14	1400	1500	930
16	1600	1600	1940

2.0 Extension of Voltage Grades

This report is applicable to other voltage grades when supply has been agreed by Sales/Production.

3.0 De-rating Factor

A blocking voltage de-rating factor of 0.13%/°C is applicable to this device for T_i below 25°C.

4.0 Repetitive dv/dt

Standard dv/dt is 1000V/µs.

5.0 Snubber Components

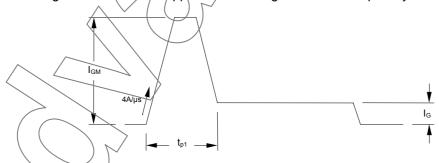
When selecting snubber components, care must be taken not to use excessively large values of snubber capacitor or excessively small values of snubber resistor. Such excessive component values may lead to device damage due to the large resultant values of snubber discharge current. If required, please consult the factory for assistance.

6.0 Rate of rise of on-state current

The maximum un-primed rate of rise of on-state current must not exceed 300A/µs at any time during turn-on on a non-repetitive basis. For repetitive performance, the on-state rate of rise of current must not exceed 150A/µs at any time during turn-on. Note that these values of rate of rise of current apply to the total device current including that from any local snubber network.

7.0 Gate Drive

The nominal requirement for a typical gate drive is illustrated below. An open circuit voltage of at least 30V is assumed. This gate drive must be applied when using the full di/dt capability of the device.



The magnitude of I_{CM} should be between five and ten times I_{GT} , which is shown on page 2. Its duration (t_{p1}) should be 20µs or sufficient to allow the anode current to reach ten times I_{L} , whichever is greater. Otherwise, an increase in pulse current could be needed to supply the necessary charge to trigger. The 'back-porch' current I_{G} should remain flowing for the same duration as the anode current and have a magnitude in the order of 1.5 times I_{GT} .

8.0 Computer Modelling Parameters

8.1 Device Dissipation Calculations

$$I_{AV} = \frac{-V_{T0} + \sqrt{{V_{T0}}^2 + 4 \cdot ff^2 \cdot r_T \cdot W_{AV}}}{2 \cdot ff^2 \cdot r_T}$$

Where V_{T0} =0.841V, r_T =0.080m Ω ,

 R_{th} = Supplementary thermal impedance, see table below and

ff = Form factor, see table below.

Supplementary Thermal Impedance							
Conduction Angle	30°	60°	/90°/	120°	180°	270°	d.c.
Square wave Double Side Cooled	0.0124	0.0122	0.0121	0.0119	0.0117	0.0113	0.0110
Square wave Single Side Cooled	0.0249	0.0248	0.0247	0.0246	0.0244	0.0241	0.022
Sine wave Double Side Cooled	0.0168	0.0140	0.0131	0.0118	0.0112		
Sine wave Single Side Cooled	0.0249	0.0247	0.0246	0.0244	0.0241		

Form Factors							
Conduction Angle	30°	60°	90°/) 1 <mark>20°</mark>	180°	270°	d.c.
Square wave	3.46	2.45	7 2	1.73	1.41	1.15	1
Sine wave	3.98	2.78	2.22	1.88	1.57		

8.2 Calculating V_T using ABCD Coefficients

- The on-state characteristic I_T vs. V_T , on page 6 is represented in two ways; (i) the well established V_{T0} and r_T tangent used for rating purposes and (ii) a set of constants A, B, C, D, forming the coefficients of the representative equation for V_T in terms of I_T given below:

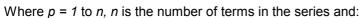
$$V_T = A + B \ln(I_T) + C \cdot I_T + D \cdot \sqrt{I_T}$$

The constants, derived by curve fitting software, are given below for both hot and cold characteristics. The resulting values for V_T agree with the true device characteristic over a current range, which is limited to that plotted.

-/				
\		25°C Coefficients		125°C Coefficients
	A	1.359308154	Α	0.619740054
	В	-0.09795577	В	7.69989×10 ³
	e	2.09655×10 ⁻⁶	С	2.95324×10 ⁻⁵
_	D	0.0107923	D	5.897501×10 ³

8.3 D.C. Thermal Impedance Calculation

$$r_t = \sum_{p=1}^{p=n} r_p \cdot \left(1 - e^{\frac{-t}{\tau_p}}\right)$$



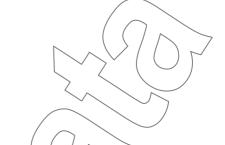
t = Duration of heating pulse in seconds.

 r_{t} = Thermal resistance at time t.

 r_p = Amplitude of p_{th} term.

 τ_p = Time Constant of r_{th} term.

The coefficients for this device are shown in the tables below:



	D.C. Double Side Cooled							
Term	1	2	3	4				
r_p	6.72×10 ⁻³	2.78×10 ⁻³	9.476×10 ⁻⁴	7.12×10 ⁻⁴				
$ au_{\!\scriptscriptstyle D}$	1.0226	0.226	0.0586	9.06×10 ⁻³				

	D.C. Single Side Cooled						
Term	1	2 3	4				
r_p	0.01688	4.42×10 ⁻³ 1.79×10 ⁻³	8.72×10 ⁻⁴				
$ au_{p}$	7.055	0.5206 0.1198	0.0128				

9.0 Reverse recovery ratings

(i) Q_{ra} is based on 50% I_{rm} chord as shown in Fig. 1

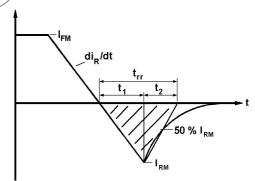
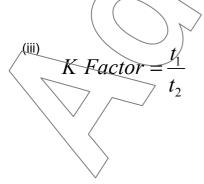


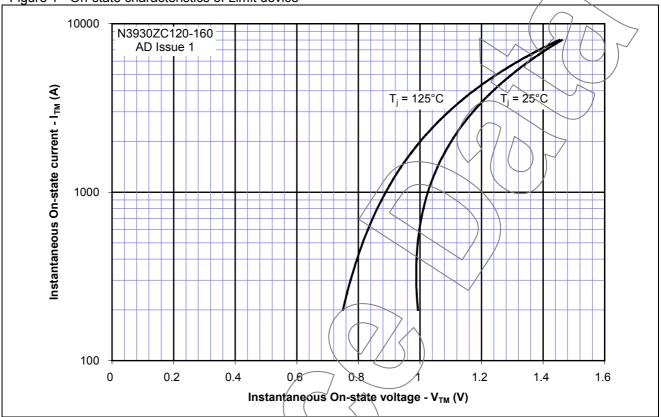
Fig. 1

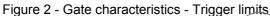


$$Q_{rr} = \int_{0}^{150 \,\mu s} i_{rr}.dt$$

Curves







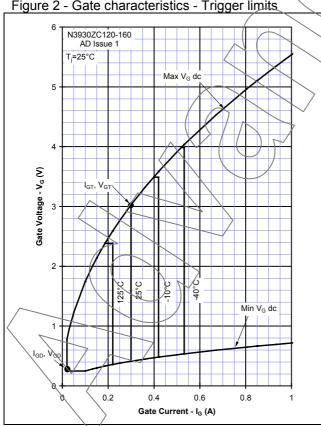
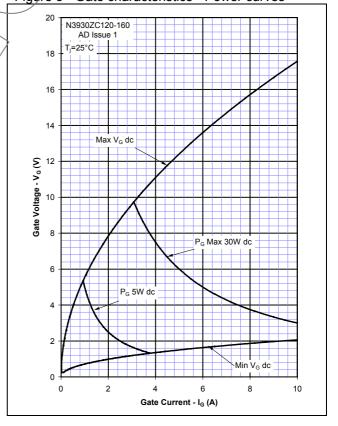
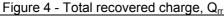


Figure 3 - Gate characteristics - Power curves





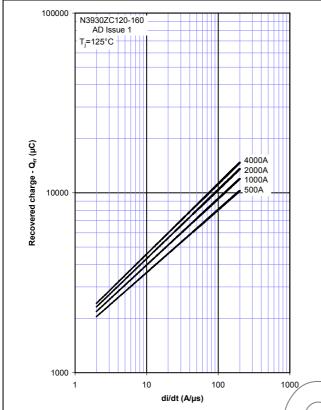
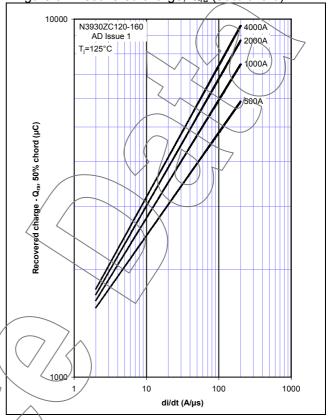


Figure 5 - Recovered charge, Q_{ra} (50% chord)



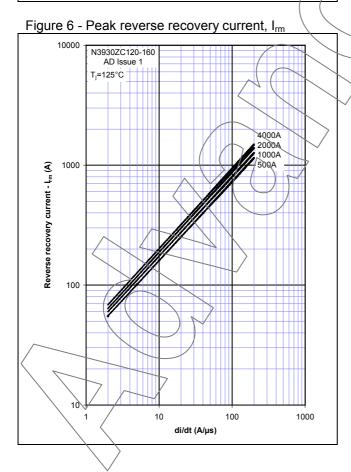


Figure 7 - Maximum recovery time, t_{rr} (50% chord)

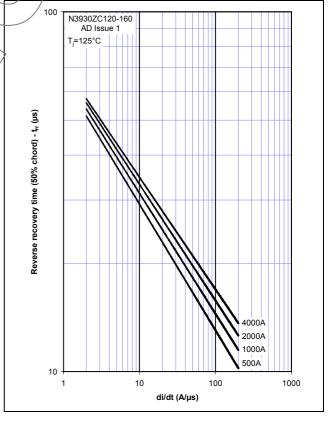


Figure 8 – On-state current vs. Power dissipation – Double Side Cooled (Sine wave)

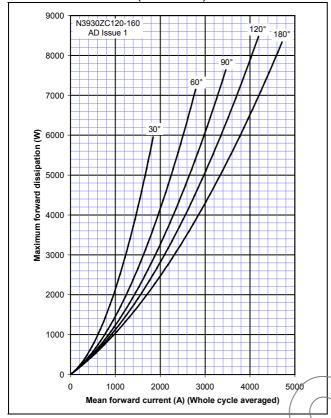


Figure 10 – On-state current vs. Power dissipation – Double Side Cooled (Square wave)

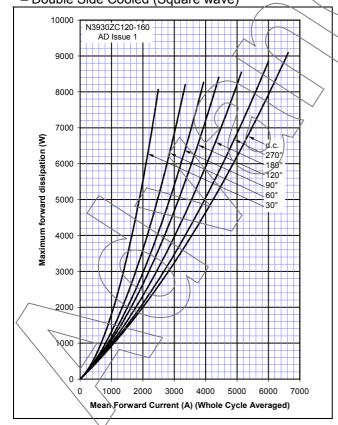


Figure 9 – On-state current vs. Heatsink temperature - Double Side Cooled (Sine wave)

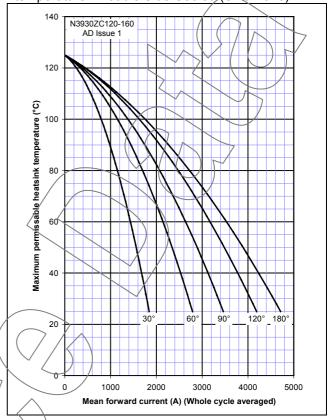


Figure 11 – On-state current vs. Heatsink temperature – Double Side Cooled (Square wave)

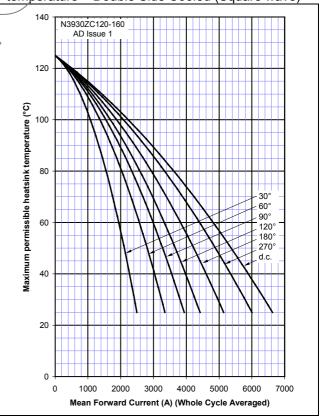


Figure 12 – On-state current vs. Power dissipation – Single Side Cooled (Sine wave)

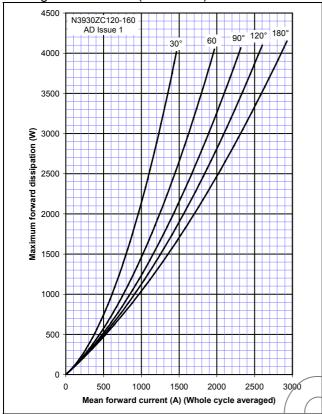


Figure 14 – On-state current vs. Power dissipation – Single Side Cooled (Square wave)

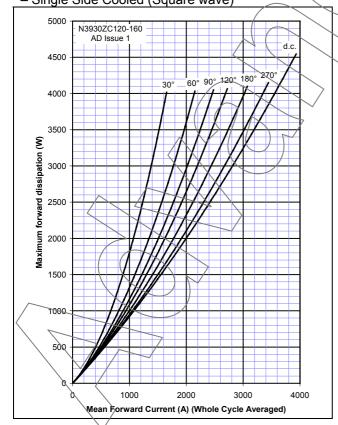


Figure 13 – On-state current vs. Heatsink temperature – Single Side Cooled (Sine wave)

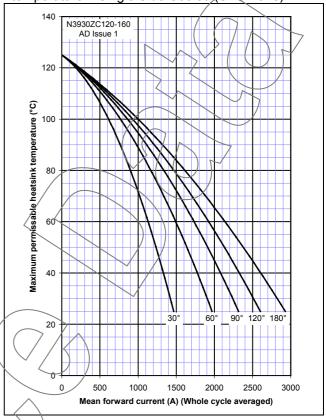
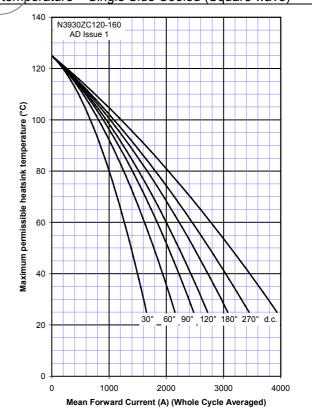
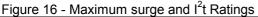
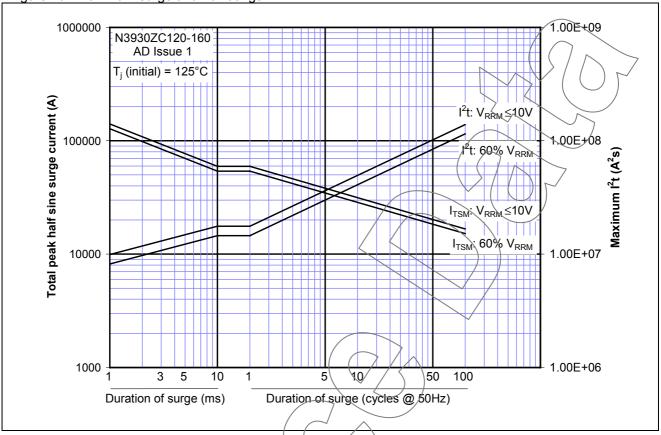
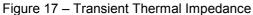


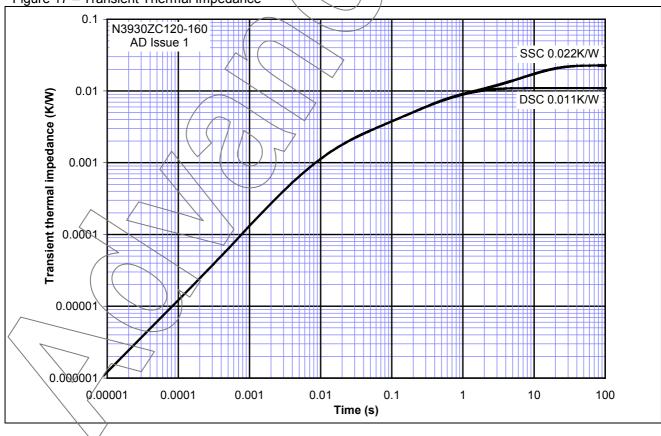
Figure 15 – On-state current vs. Heatsink temperature – Single Side Cooled (Square wave)



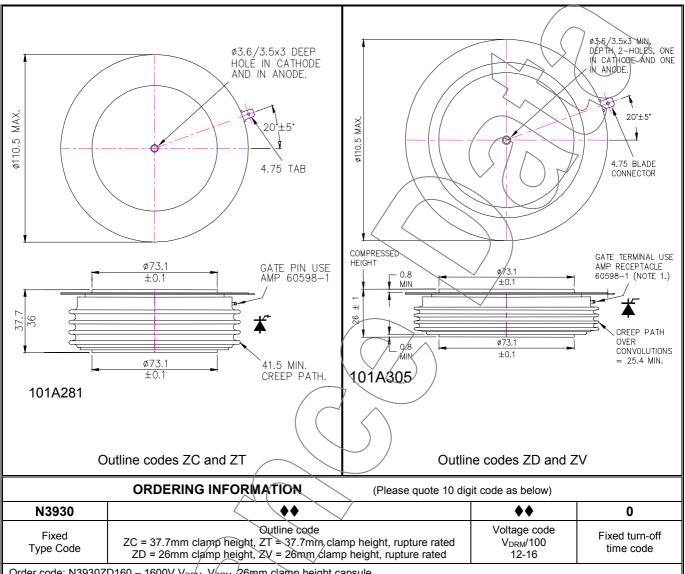








Outline Drawing & Ordering Information



Order code: N3930ZD160 – 1600V V_{DRM}, V_{RRM}, 26mm clamp height capsule.

IXYS Semiconductor GmbH

Edisonstraße 15 D-68623 Lampertheim Tel: +49 6206 503-0 Fax: +49 6206 503-627 E-mail: marcom@ixys.de



IXYS Corporation 3540 Bassett Street, Santa Clara CA 95054 /USA

Tel: +1 (408) 982 0700 Fax: +1 (408) 496 0670 E-mail: sales@ixys.net

www.westcode.com

www.ixys.com

Westcode Semiconductors Ltd

Langley Park Way, Langley Park, Chippenham, Wiltshire, SN15 1GE. Tel: +44 (0)1249 455500 Fax: +44 (0)1249 659448

E-mail: WSL.sales@westcode.com

Westcode Semiconductors Inc

3270 Cherry Avenue Long Beach CA 90807 USA Tel: +1 (562) 595 6971 Fax: +1 (562) 595 8182

E-mail: WSI.sales@westcode.com

The information contained herein is confidential and is protected by Copyright. The information may not be used or disclosed except with the written permission of and in the manner permitted by the proprietors Westcode Semiconductors Ltd.

est of product improvement, Westcode reserves the right to change specifications at any time without prior notice.

Devices with a suffix code/2-letter, 3-letter or letter/digit/letter combination) added to their generic code are not necessarily subject to the conditions and limits con(ained in this report.

© Westcode Semiconductors Ltd.